

U_FPGA_IO
FPGA_IO.SchDoc

U_B2B_Connector
B2B_Connector.SchDoc

U_FPGA_MGT
FPGA_MGT.SchDoc

U_POWER
POWER.SchDoc

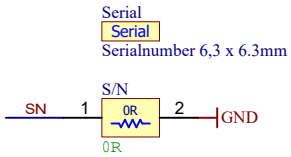
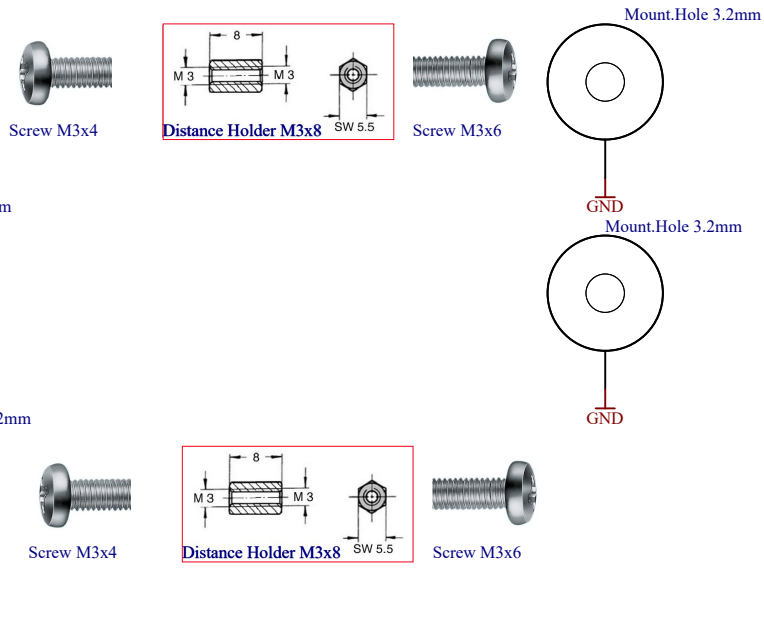
U_FPGA_MISC
FPGA_MISC.SchDoc

U_Revision
Revision_Changes.SchDoc

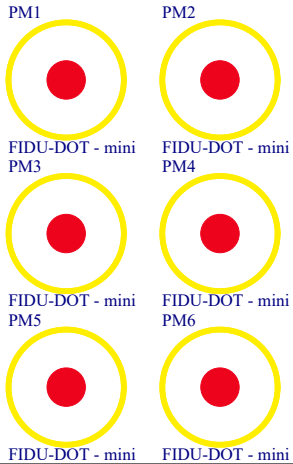
Special notes:

-
-

Top of Board

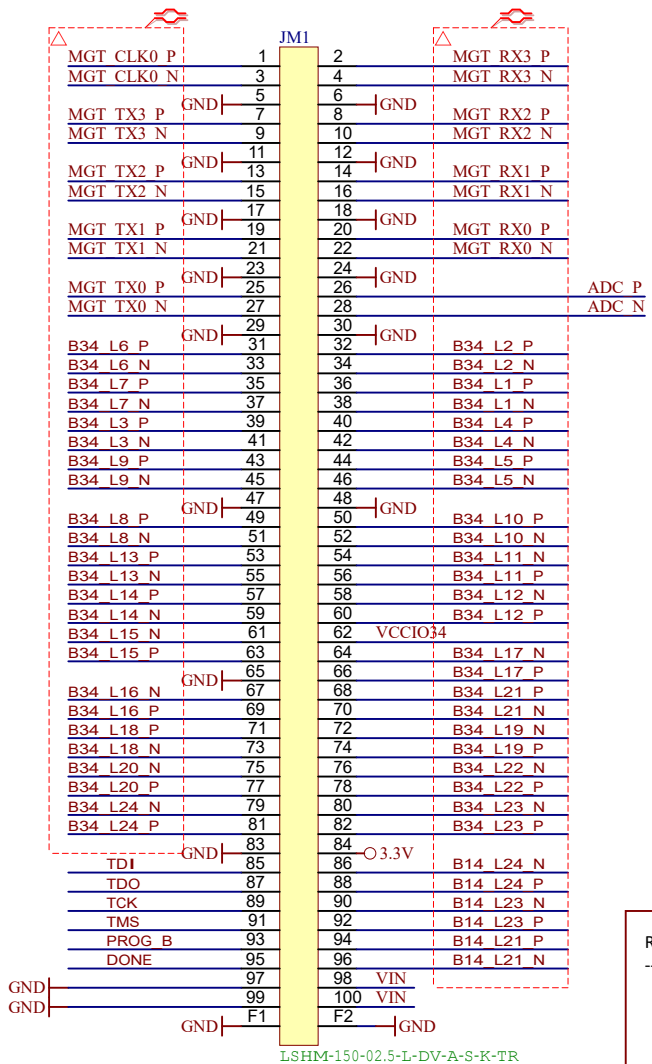


LOGO1
TE Logo PRINT Layer
LOGO PRINT



Assembly variant	S002
Created by	
Modified by	
Modified at	
SVN Revision	8634

	Title: TE0714	
	A4	Number: TE0714 S002
	Date: 2019-02-14	Rev. 03
	Copyright: Trenz Electronic GmbH / TT	Page1 of 7
Filename: TE0714.SchDoc		

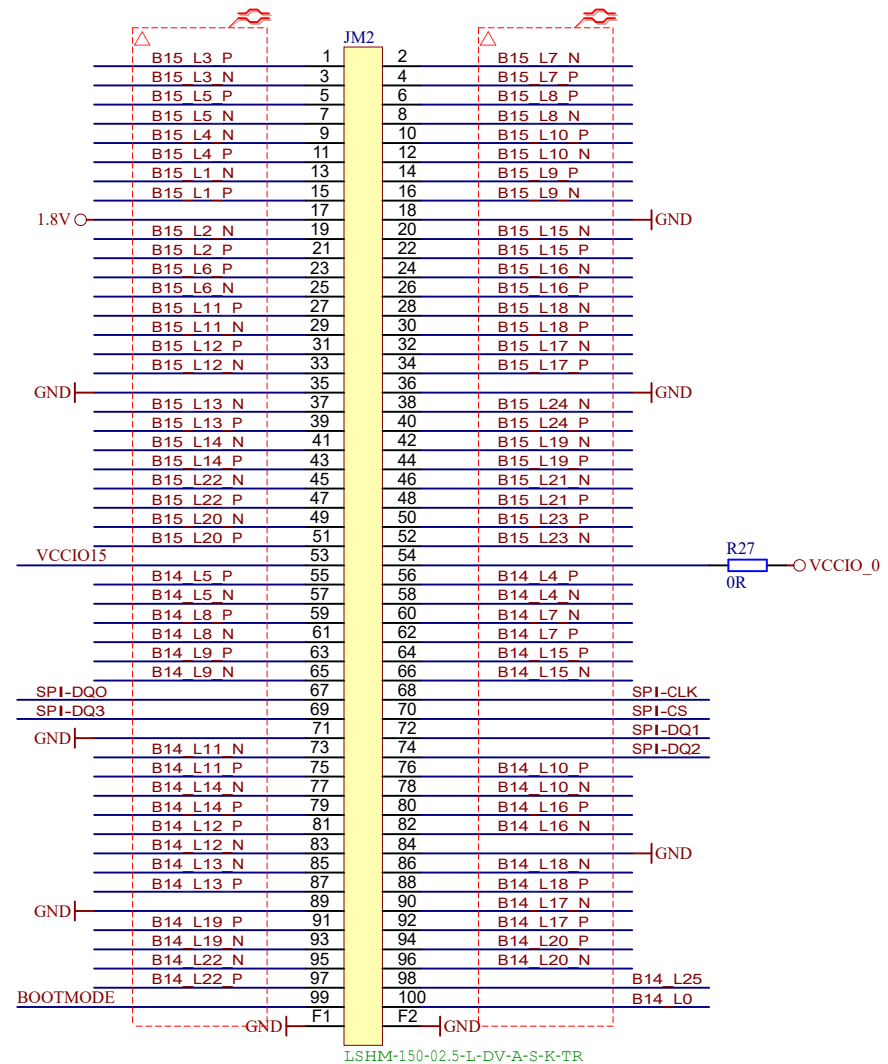


LSHM-150-02.5-L-DV-A-S-K-TR

R21 | R22 | R24 | R25 | R27 | *JM2 pin 54 function

+	+	-	+	-	+	3.3V Power OUTPUT
-	-	+	-	+	+	1.8V Power OUTPUT
-	-	+	-	+	+	2.5V/3.3V Power Input
-	-	-	+	+	+	1.8V Power Input
?	?	?	?	?	-	Not connected

Bank 0
Bank 14



LSHM-150-02.5-L-DV-A-S-K-TR

Title: TE0714

A4	Number: TE0714 S002	Rev. 03
Date: 2019-02-14	Copyright: Trenz Electronic GmbH / TT	Page2 of 7
Filename: B2B_Connector.SchDoc		

A

B

C

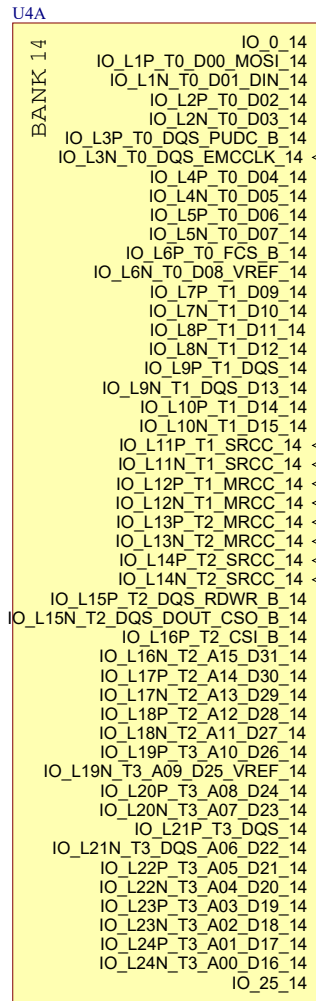
D

A

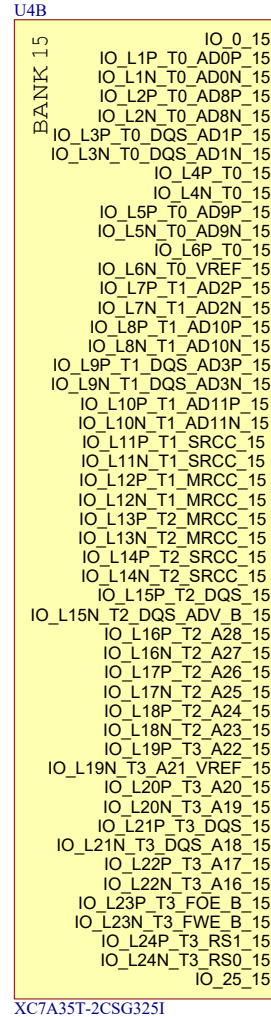
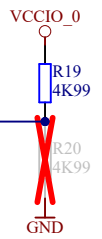
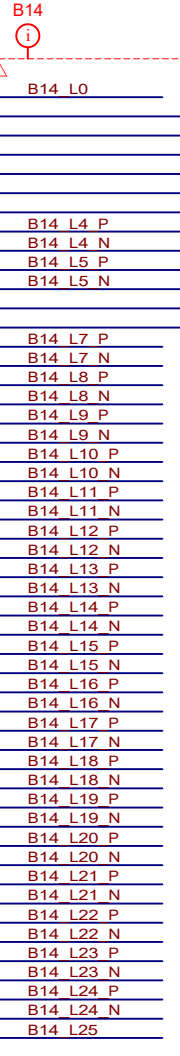
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C

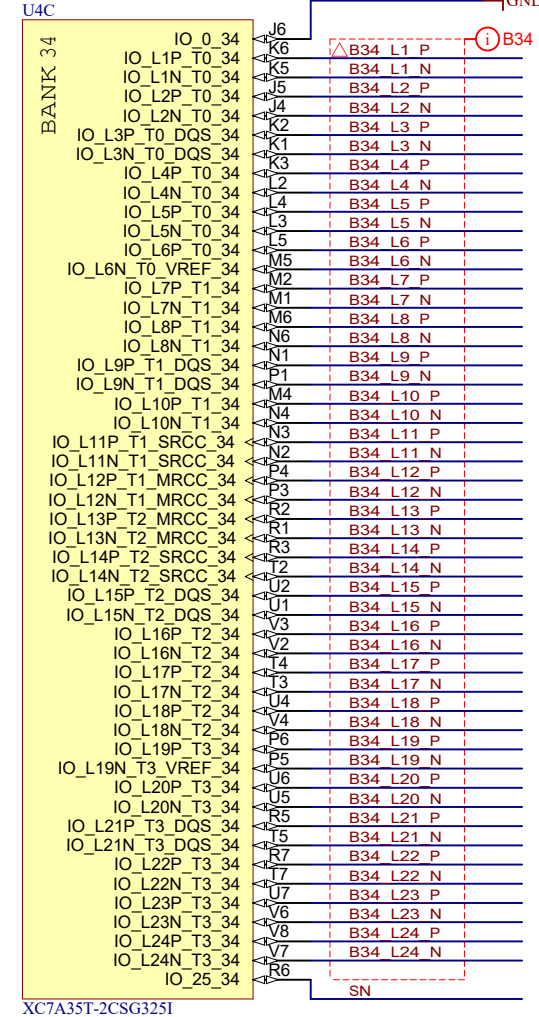
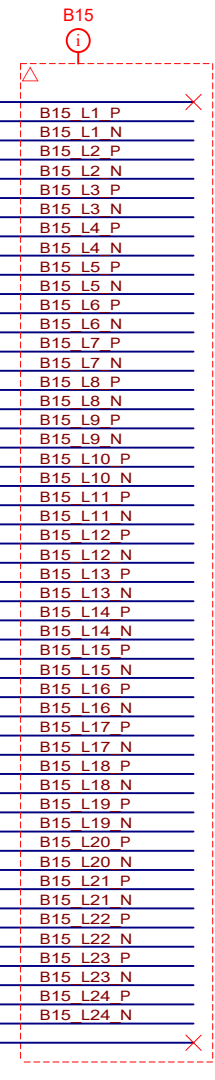
D



XC7A35T-2CSG325I

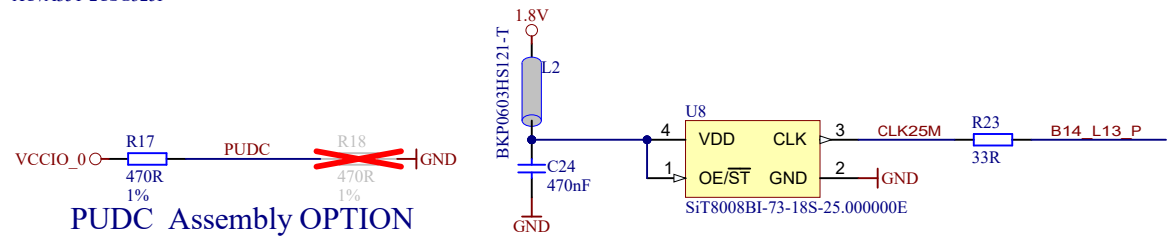
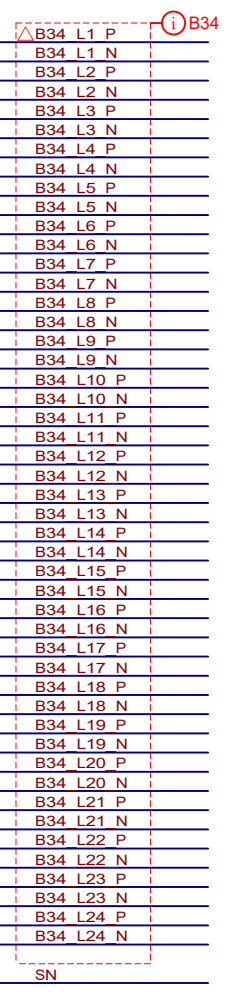


XC7A35T-2CSG325I



XC7A35T-2CSG325I

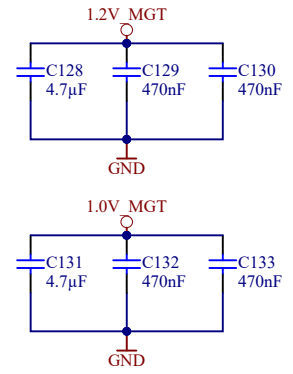
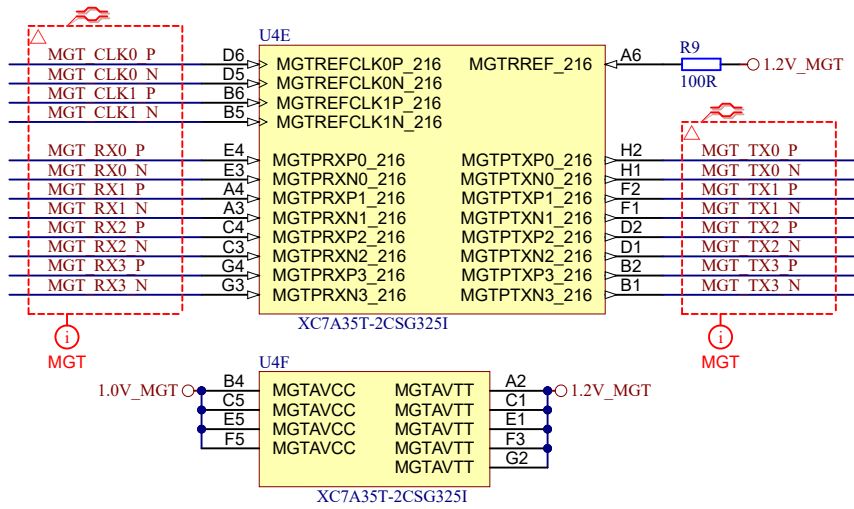
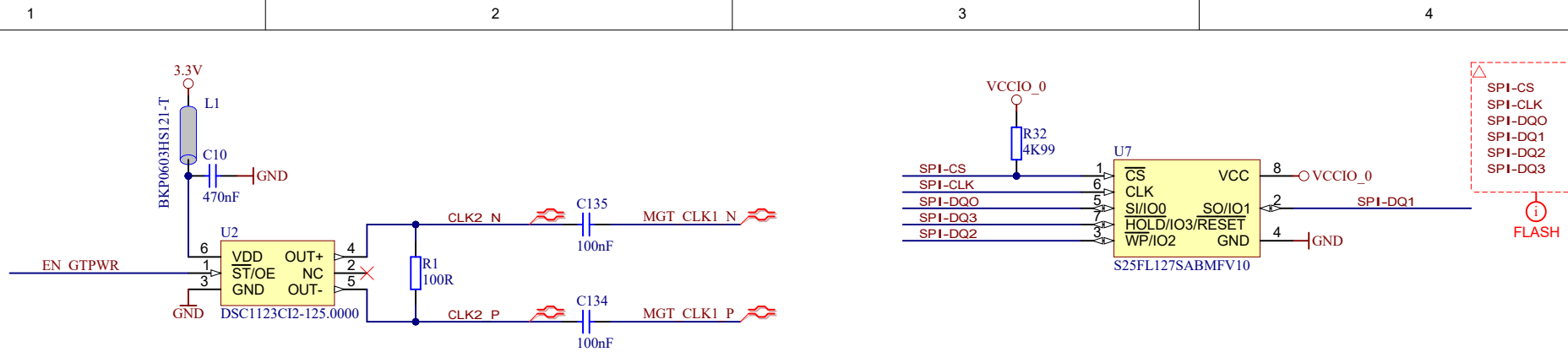
PCB REVID 0



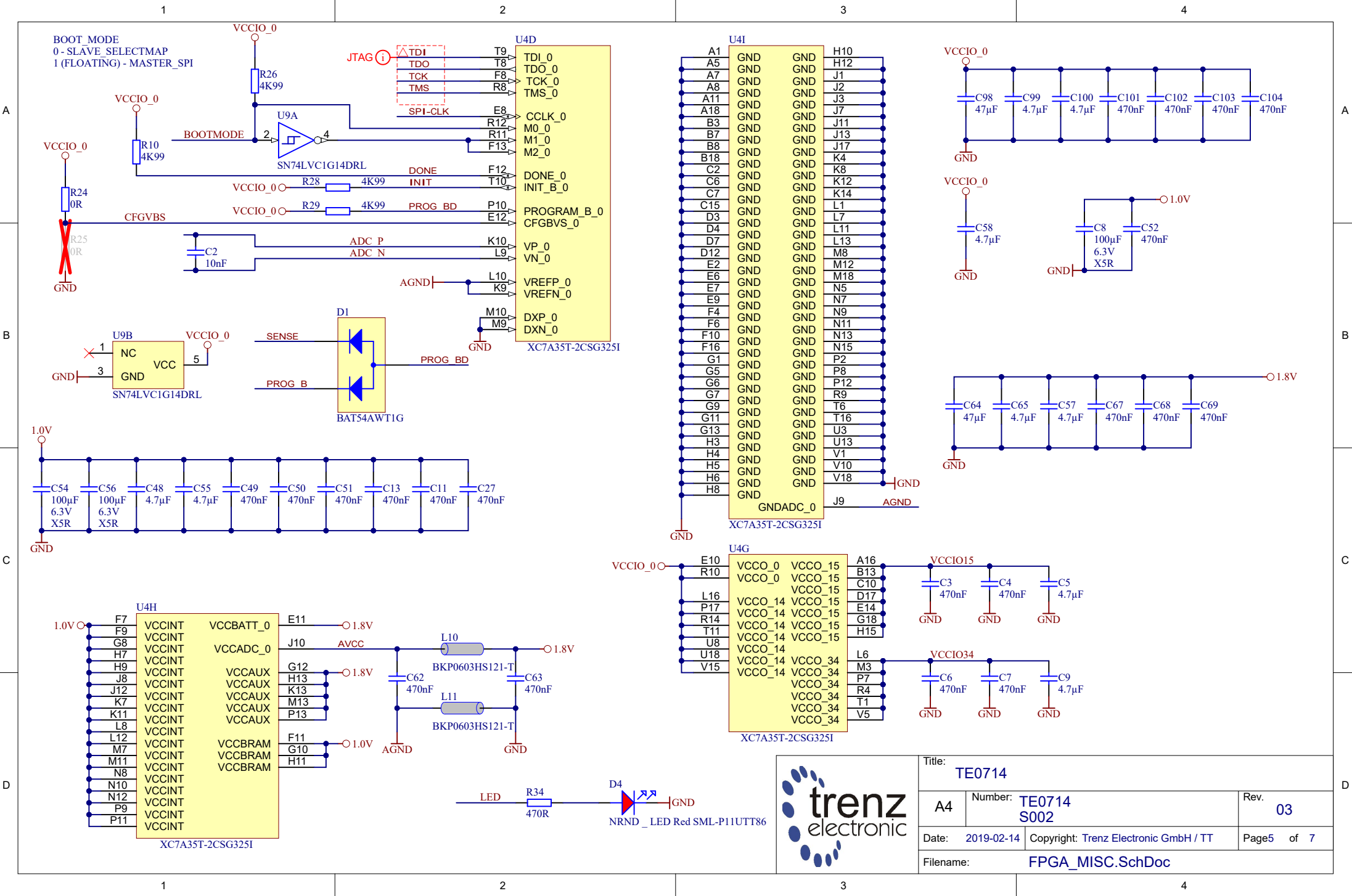
PUDC Assembly OPTION



Title: TE0714		Rev. 03	
A4	Number: TE0714 S002	Page 3 of 7	
Date: 2019-02-14	Copyright: Trenz Electronic GmbH / TT		Page 3 of 7
Filename: FPGA_IO.SchDoc			

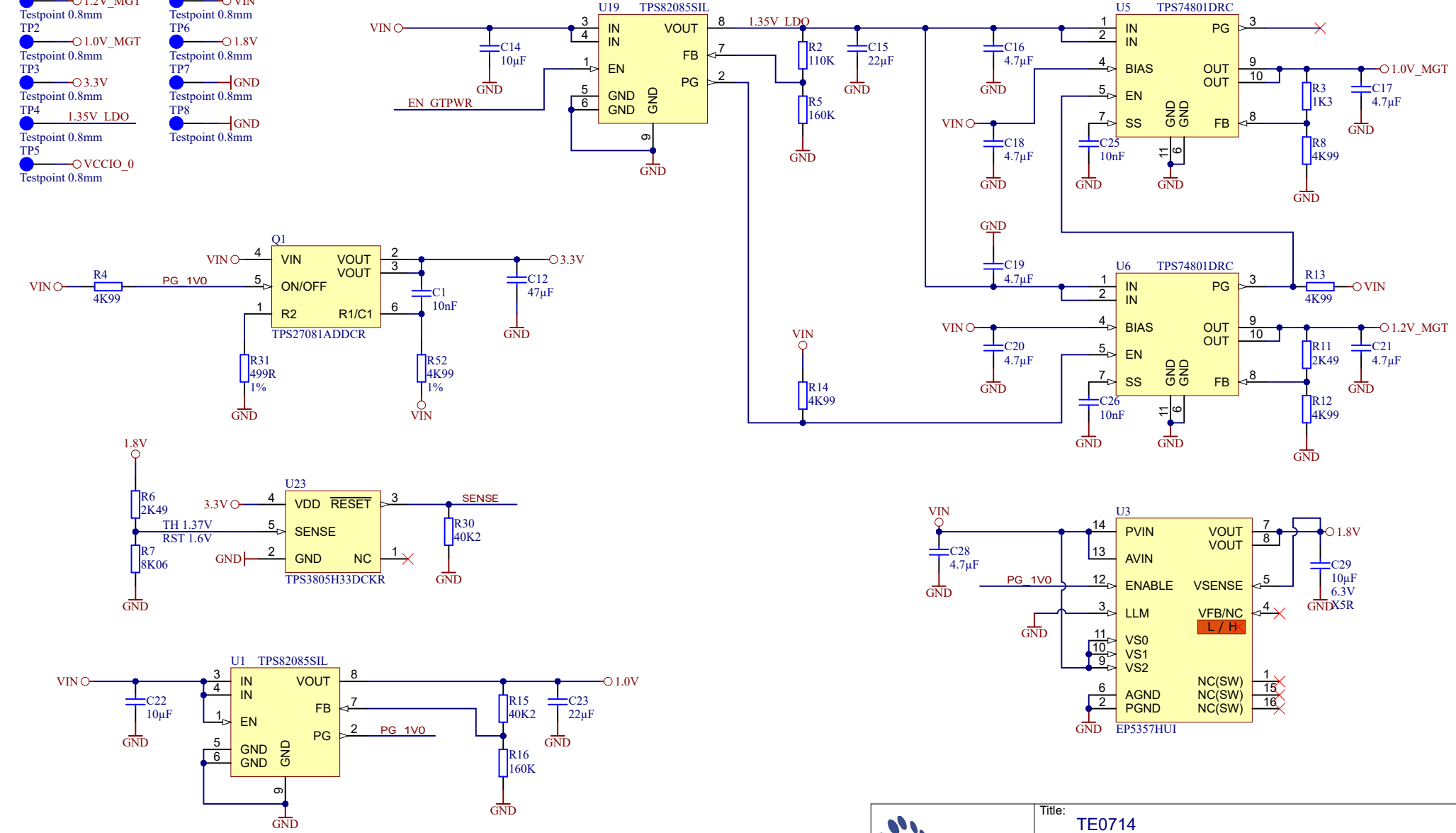


	Title: TE0714		
	A4	Number: TE0714 S002	Rev. 03
	Date: 2019-02-14	Copyright: Trenz Electronic GmbH / TT	Page 4 of 7
	Filename: FPGA_MGT.SchDoc		



Title: TE0714		
A4	Number: TE0714 S002	Rev. 03
Date: 2019-02-14	Copyright: Trenz Electronic GmbH / TT	Page5 of 7
Filename: FPGA_MISC.SchDoc		

- TP1 ● ○ 1.2V_MGT
Testpoint 0.8mm
- TP2 ● ○ 1.0V_MGT
Testpoint 0.8mm
- TP3 ● ○ 3.3V
Testpoint 0.8mm
- TP4 ● ○ 1.35V_LDO
Testpoint 0.8mm
- TP5 ● ○ VCCIO_0
Testpoint 0.8mm
- TP9 ● ○ VIN
Testpoint 0.8mm
- TP6 ● ○ 1.8V
Testpoint 0.8mm
- TP7 ● ○ GND
Testpoint 0.8mm
- TP8 ● ○ GND
Testpoint 0.8mm



Title: TE0714		
A4	Number: TE0714 S002	Rev. 03
Date: 2019-02-14	Copyright: Trenz Electronic GmbH	
Filename: POWER.SchDoc		Page 6 of 7

Changes REV 02:


- 1. Added 0 ohm strap option to supply VCCIO0 on B2B connector
- 2. Added PCB Revision sense support. PCB Revision readout possible from HDL Design
- 3. Updated FPGA pin PROG_B connection. TPS3805H33 push-pull output RESET_N not affected on baseboard circuit, connected to PROG_B.
- 4. C8, C54, C56 updated to 100uF for variant 50-2I
- 5. Added testpoints

Changes REV 02A (12.2018):

- 1. New FLASH memory U7 S25FL127SABMFV10

Changes REV 03:

- 1) Changed obsolete component U3 (LXDC2HL18A-052 -> EP5357HUI)
- 2) DXP/DXN connected to GND (recommendation UG475, p31)
- 3) Added serial number to silk
- 4) Changed obsolete component Q1 (TPS27082LDDCR ->TPS27081ADDCR)
- 5) Full update LIB
- 6) Optimized testpoints placement

	Title: TE0714		
	A4	Number: TE0714 S002	Rev. 03
	Date: 2019-02-14	Copyright: Trenz Electronic GmbH / TT	Page 7 of 7
	Filename: Revision Changes.SchDoc		